

# **Final Product Change Notification**

Issue Date: 13-May-2020 Effective Date: 11-Aug-2020

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# QUALITY

202003043F01

**Management Summary** 

Cu Wire is being added as a wirebond material option for LPC5410x, LPC5411x and LPC51U68 in LQFP64 packages at assembly site NXP-ATKH.

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[] Wafer Fab Process	[] Assembly [X] Product Marking	[] Test	[] Design
	Process	Location	
[] Wafer Fab Materials	[X] Assembly [] Mechanical Specification	on[]Test	[] Errata
	Materials	Process	
[] Wafer Fab Location	[] Assembly []	[]Test	[] Electrical
	Location Packing/Shipping/Labelin	g Equipment	•
			coverage
[] Firmware	[] Other		

LPC5410x, LPC5411x, LPC51U68 LQFP64 Package Cu Wire Qualification for NXP-ATKH

### **Description of Change**

Copper wire has been qualified and will be added as a wirebond material. Upon effective date, NXP will begin shipping product with copper wire.

Die attach glue and mold compound have been upgraded to support copper wire.

See attached Self Qualification Reports (SQR) for details of the reliability qualification test results.

Samples of the following superset part numbers will be available:

LPC54114J256BD64

LPC54102J512BD64

LPC51U68FBD64

### Reason for Change

Adding Copper wire is for supply assurance.

# **Identification of Affected Products**

Top side marking

Product version is incremented. See marking details in attached Self Qualification Report (SQR) document.

### **Product Availability**

Samples are available from 22-May-2020

### **Production**

Planned first shipment 09-Aug-2020

# Anticipated Impact on Form, Fit, Function, Reliability or Quality

The top side marking, wire composition, die attach glue and mold compound are the only changes. No Impact to fit, function or reliability.

# **Data Sheet Revision**

No impact to existing datasheet

# **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 12-Jun-2020.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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# **Affected Part Numbers**

LPC54101J256BD64QL

LPC54101J512BD64QL

LPC54102J256BD64QL

LPC51U68JBD64QL

LPC54114J256BD64QL

LPC54113J256BD64QL

LPC54102J512BD64QL